

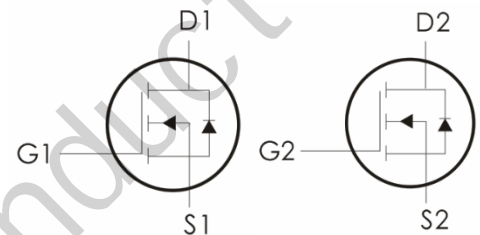
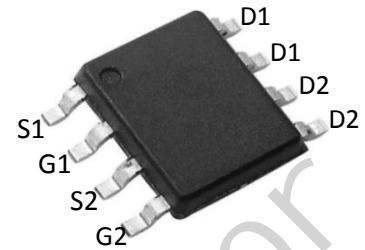
Description:

This Dual N-Channel MOSFET uses advanced trench technology and design to provide excellent $R_{DS(ON)}$ with low gate charge.

It can be used in a wide variety of applications.

Features:

- 1) $V_{DS}=60V, I_D=4.5A, R_{DS(ON)}<36m\Omega @V_{GS}=10V$
- 2) Low gate charge.
- 3) Green device available.
- 4) Advanced high cell density trench technology for ultra low $R_{DS(ON)}$.
- 5) Excellent package for good heat dissipation.



Absolute Maximum Ratings: ($T_A=25^\circ\text{C}$ unless otherwise noted)

Symbol	Parameter	Ratings	Units
V_{DS}	Drain-Source Voltage	60	V
V_{GS}	Gate-Source Voltage	± 20	V
I_D	Continuous Drain Current - $T_A=25^\circ\text{C}^1$	4.5	A
	Continuous Drain Current - $T_A=70^\circ\text{C}^1$	3.5	
I_{DM}	Drain Current-Pulsed ²	18	A
E_{AS}	Single Pulse Avalanche Energy ³	22	mJ
I_{AS}	Avalanche Current	21	A
P_D	Power Dissipation ⁴	1.5	W
T_J, T_{STG}	Operating and Storage Junction Temperature Range	-55 to +150	$^\circ\text{C}$

Thermal Characteristics:

Symbol	Parameter	Max	Units
$R_{\theta JA}$	Thermal Resistance, Junction to Ambient ¹	85	$^\circ\text{C}/\text{W}$

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Symbol	Parameter	Max	Units
$R_{\theta JA}$	Thermal Resistance, Junction to Ambient ¹	85	°C/W
$R_{\theta JC}$	Thermal Resistance Junction-Case ¹	25	°C/W

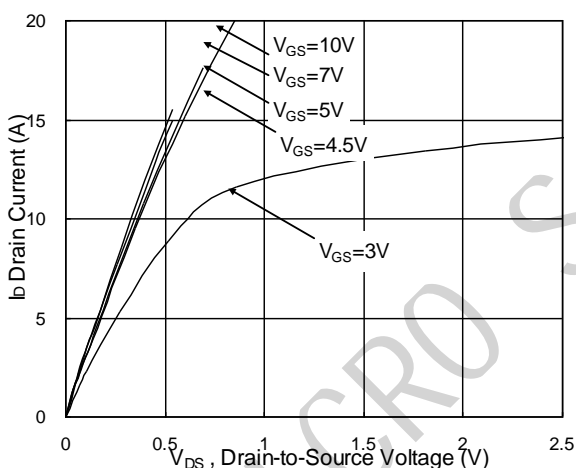
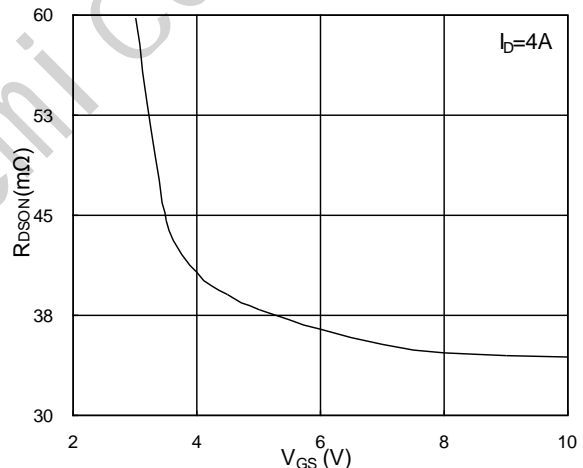
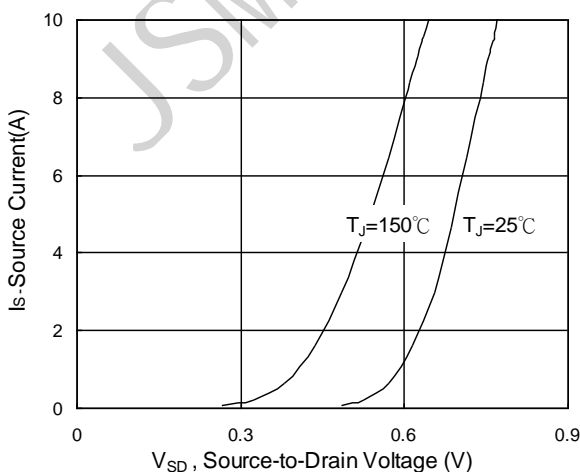
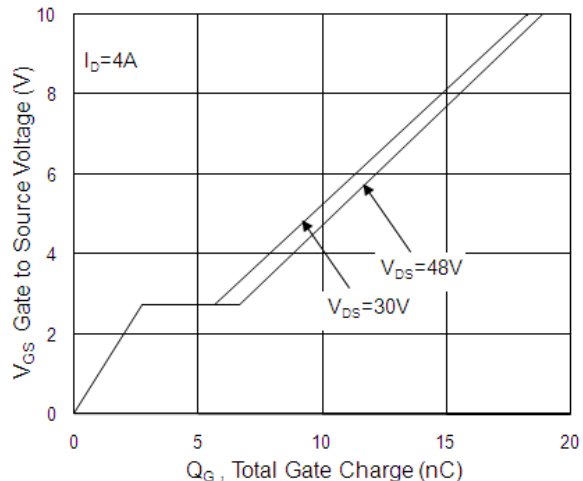
Electrical Characteristics: ($T_C=25^\circ\text{C}$ unless otherwise noted)

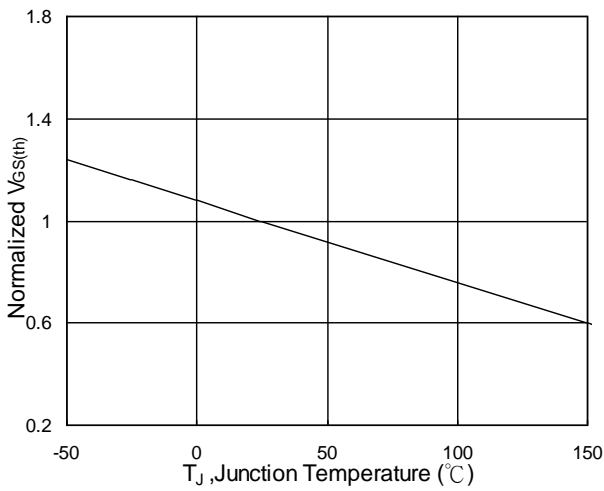
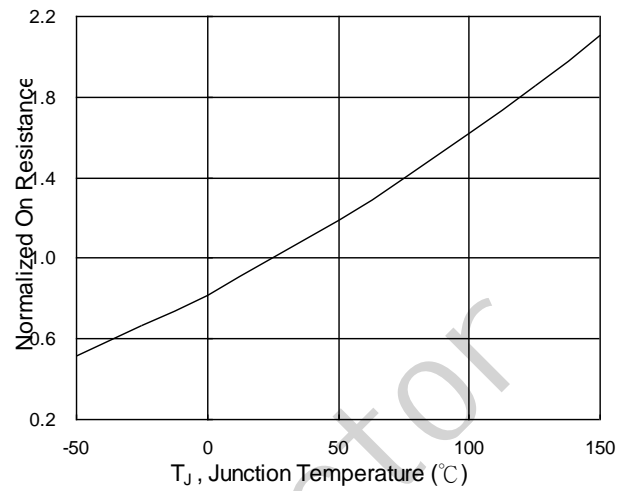
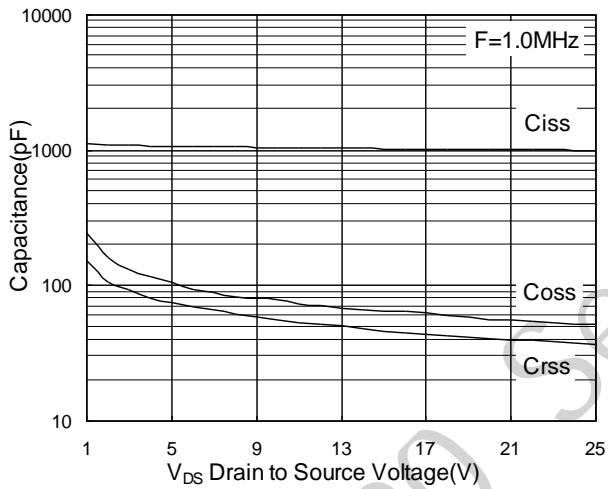
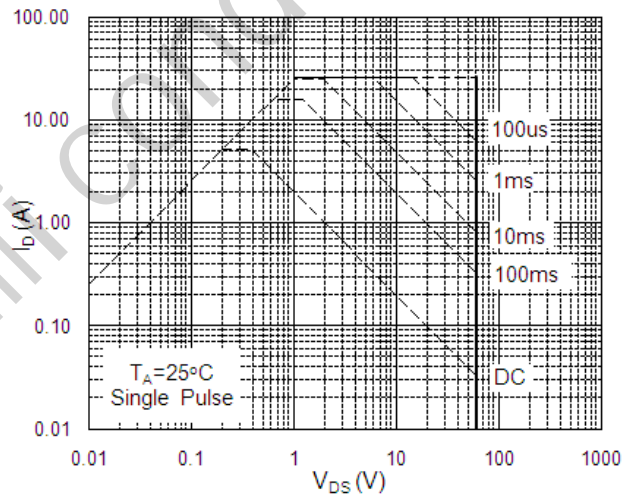
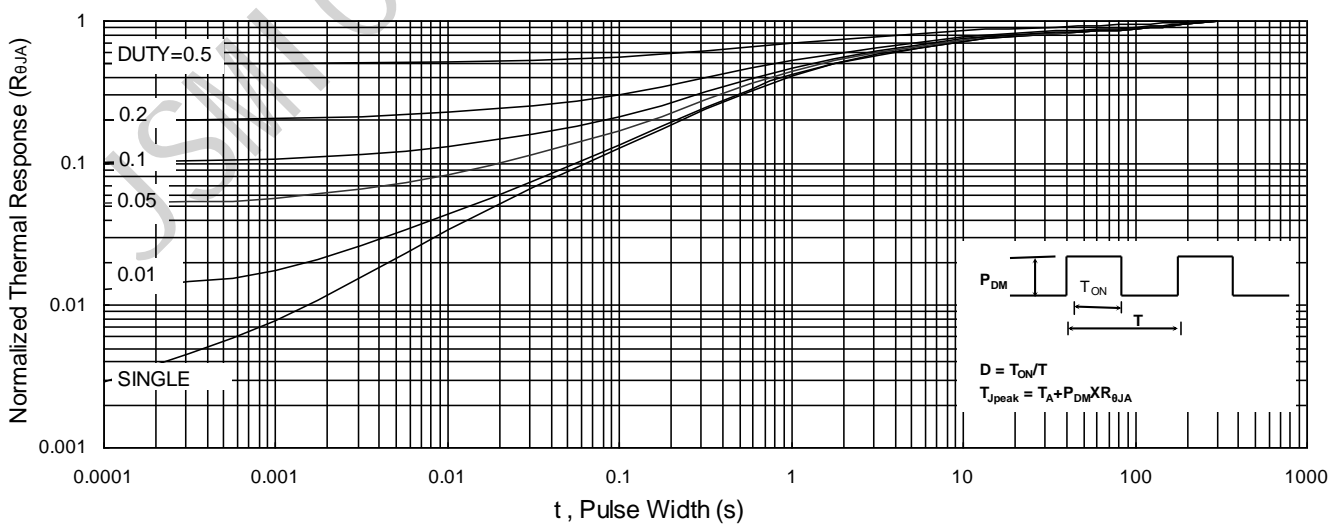
Symbol	Parameter	Conditions	Min	Typ	Max	Units
Off Characteristics						
BV_{DSS}	Drain-Source Breakdown Voltage	$V_{GS}=0V, I_D=250 \mu A$	60	---	---	V
I_{DSS}	Zero Gate Voltage Drain Current	$V_{GS}=0V, V_{DS}=48V, T_J=25^\circ\text{C}$	---	---	1	μA
		$V_{GS}=0V, V_{DS}=48V, T_J=55^\circ\text{C}$	---	---	5	μA
I_{GSS}	Gate-Source Leakage Current	$V_{GS}=\pm 20V, V_{DS}=0A$	---	---	± 100	nA
On Characteristics						
$V_{GS(th)}$	GATE-Source Threshold Voltage	$V_{GS}=V_{DS}, I_D=250 \mu A$	1	---	2.5	V
$R_{DS(on)}$	Drain-Source On Resistance	$V_{GS}=10V, I_D=4A$	---	30	36	m Ω
		$V_{GS}=4.5V, I_D=3A$	---	34	45	
G_{FS}	Forward Transconductance	$V_{DS}=5V, I_D=4A$	---	28.3	---	S
Dynamic Characteristics						
C_{iss}	Input Capacitance	$V_{DS}=15V, V_{GS}=0V, f=1\text{MHz}$	---	1020	---	pF
C_{oss}	Output Capacitance		---	60	---	
C_{rss}	Reverse Transfer Capacitance		---	45	---	
Switching Characteristics						
$t_{d(on)}$	Turn-On Delay Time	$V_{DD}=30V, I_D=4A$ $R_G=3.3 \Omega, V_{GS}=10V,$	---	3	---	ns
t_r	Rise Time		---	34	---	ns
$t_{d(off)}$	Turn-Off Delay Time		---	23	---	ns
t_f	Fall Time		---	6	---	ns
Q_g	Total Gate Charge		$V_{GS}=10V, V_{DS}=48V,$	---	19	---
Q_{gs}	Gate-Source Charge	$I_D=4A$	---	2.6	---	nC

Q_{gd}	Gate-Drain "Miller" Charge		---	4.1	---	nC
R_G	Gate Resistance	V _{DS} =0V, V _{GS} =0V, f=1MHz	---	2.5	---	Ω
Drain-Source Diode Characteristics						
V_{SD}	Source-Drain Diode Forward Voltage ²	V _{GS} =0V, I _S =1A, T _J =25°C	---	---	1.2	V
I_S	Continuous Source Current ^{1,5}	V _G =V _D =0V, Force Current	---	---	4.5	A
I_{SM}	Pulsed Source Current ^{2,5}		---	---	18	A
T_{rr}	Reverse Recovery Time	I _F =4A, di/dt=100A/μs, T _J =25°C	---	12.1	---	ns
Q_{rr}	Reverse Recovery Charge		---	6.7	---	nC

Notes:

1. The data tested by surface mounted on a 1 inch² FR-4 board with 2OZ copper.
2. The data tested by pulsed, pulse width ≤ 300us, duty cycle ≤ 2%
3. The EAS data shows Max. rating. The test condition is V_{DD}=25V, V_{GS}=10V, L=0.1mH, I_{AS}=21A
4. The power dissipation is limited by 150°C junction temperature
5. The data is theoretically the same as I_D and I_{DM}, in real applications, should be limited by total power dissipation.

Typical Characteristics: (T_C=25°C unless otherwise noted)

Fig.1 Typical Output Characteristics

Fig.2 On-Resistance vs. Gate-Source

Fig.3 Forward Characteristics Of Reverse

Fig.4 Gate-Charge Characteristics


Fig.5 Normalized $V_{GS(th)}$ vs. T_J

Fig.6 Normalized $R_{DS(on)}$ vs. T_J

Fig.7 Capacitance

Fig.8 Safe Operating Area

Fig.9 Normalized Maximum Transient Thermal Impedance

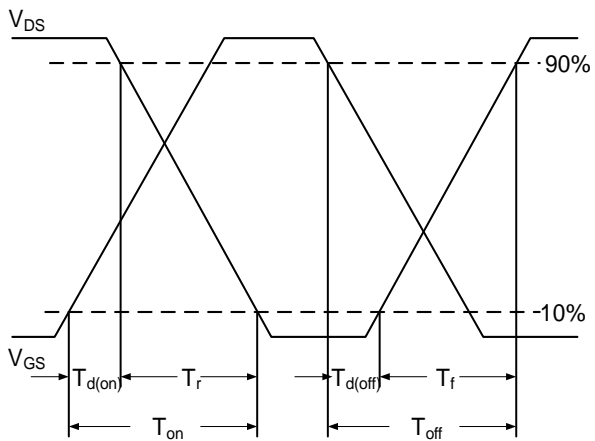


Fig.10 Switching Time Waveform

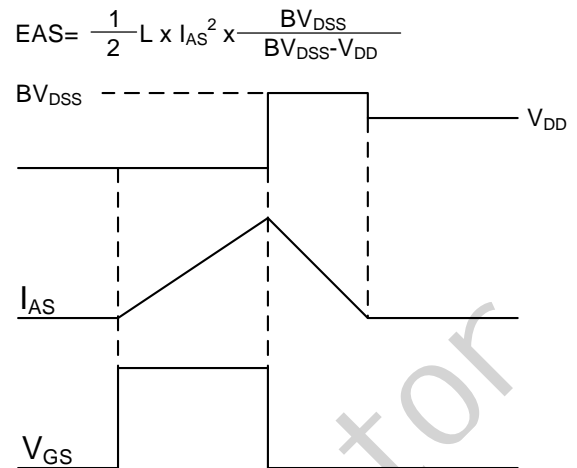
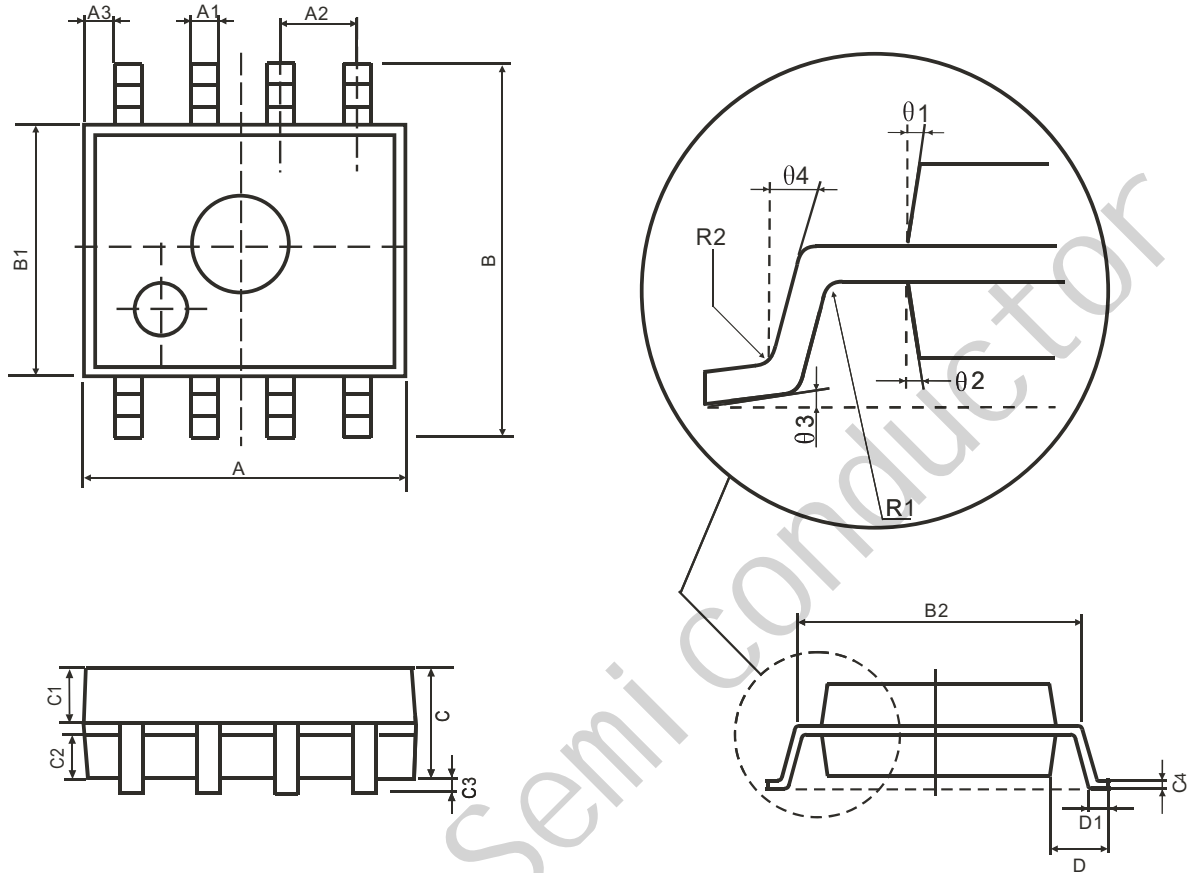


Fig.11 Unclamped Inductive Switching Waveform

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符号	尺寸(mm)		符号	尺寸(mm)	
	最小值	最大值		最小值	最大值
A	4.95	5.15	C3	0.05	0.20
A1	0.37	0.47	C4	0.20(典型值)	
A2	1.27(典型值)		D	1.05(典型值)	
A3	0.41(典型值)		D1	0.40	0.60
B	5.80	6.20	R1	0.07(典型值)	
B1	3.80	4.00	R2	0.07(典型值)	
B2	5.0(典型值)		theta1	17°(典型值)	
C	1.30	1.50	theta2	13°(典型值)	
C1	0.55	0.65	theta3	4°(典型值)	
C2	0.55	0.65	theta4	12°(典型值)	

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